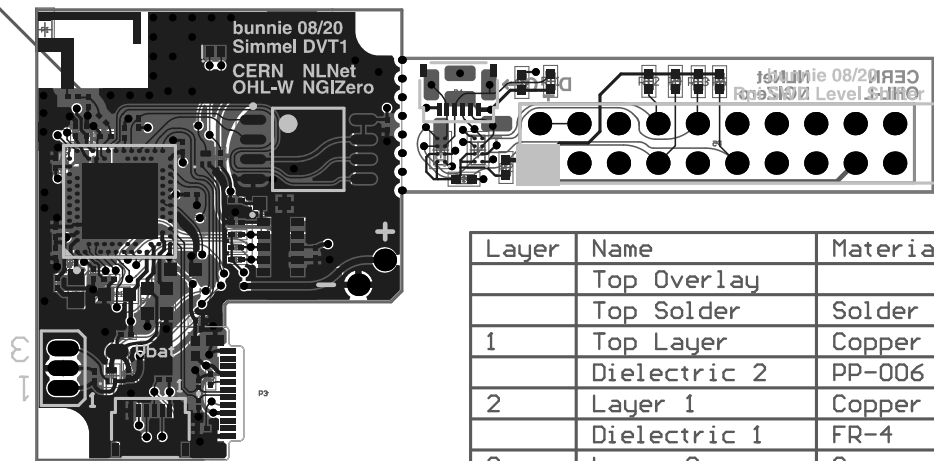


Title Simmel - Debug		
Size A	Number	Revision
Date: 8/18/2020	Sheet of	
File: F:\largework\...\debug.SchDoc	Drawn By:	

0.123mm => 50 ohm +/-10% impedance  
top side only



Route outline along midline

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 2	PP-006	0.071mm	4.1	
2	Layer 1	Copper	0.035mm		
	Dielectric 1	FR-4	0.500mm	4.8	
3	Layer 2	Copper	0.035mm		
	Dielectric 3	PP-006	0.071mm	4.1	
4	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				

Total board thickness: 0.804mm

Solder mask white  
Silkscreen red  
Finish ENIG